

40G-QSFP-SR4

QSFP+ SR4 40G,150M,850nm,MPO

Features

- Support 40GBASE-SR4/QDR application
- Compliant to QSFP+ Electrical MSA SFF-8436
- Multi rate of up to 10.3125Gbps per lane
- Transmission distance up to 150m (OM3)
- +3.3V single power supply
- Low power consumption
- Operating case temp
- Commercial: 0°C to +70 °C
- RoHS compliant



Applications

- 40GBASE-SR4 at 10.3125Gbps per lane
- InfiniBand QDR
- Other optical links

Table 1- Order Information

Part No.	Bit Rate Per Lane (Gbps)	Laser (nm)	Distance	Fiber Type	DDMI	Connector	Temp ^{note1}
40G-QSFP-SR4	10.3125	850	150m	MMF	YES	MPO 1x12	0°C~+70°C

Note:

1. Case Temperature

Absolute Maximum Ratings

Table2- Absolute Maximum Ratings

Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Supply Voltage	V _{cc3}	-0.5	-	+3.6	V	
Storage Temperature	T _s	-40	-	+85	°C	
Operating Humidity	RH	+5	-	+85	%	1
Receiver Damage Threshold per Lane	P _{IND}	+3.4	-	-	dBm	

Note:

1. No condensation

Recommended Operating Conditions

Table 3- Recommended operating Conditions

Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Operating Case Temperature	T _C	0	-	+70	°C	
Power Supply Voltage	V _{cc}	3.14	3.3	3.47	V	
Power Dissipation	P _d	-	-	1.5	W	
Bit Rate	BR	1.25	10.3125	-	Gbps	Per lane

Electrical Characteristics

Table 4- Electrical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Units	Notes
Input Logic Level High	V_{IH}	2.0	-	$V_{CC}+0.3$	V	
Input Logic Level Low	V_{IL}	$V_{EE}-0.3$	-	0.8	V	
Output Logic Level High	V_{OH}	2.0	-	$V_{CC}+0.3$	V	
Output Logic Level Low	V_{OL}	$V_{EE}-0.3$	-	0.4	V	
Transmitter						
Differential Data Input Swing	$V_{in,P-P}$	200	-	1000	mV _{pp}	
Input Differential Impedance	Z_{IN}	90	100	110	Ω	
Receiver						
Differential Date Output Swing	V_{out}	200	-	1000	mV	
Output Differential Impedance	Z_D	90	100	110	Ω	

Optical Characteristics

Table 5-Optical Characteristics

Parameter	Symbol	Unit	Min	Typ	Max	Notes
Optical transmitter Characteristics						
Bit Rate	BR	Gbps	1.25	10.3125	-	Per lane
Center Wavelength Range	λ_c	nm	840	850	860	
RMS Spectral Width	$\Delta\lambda$	nm	-	-	0.6	
Average Launch power Tx_off	P _{off}	dBm	-	-	-30	
Launch Optical Power	P ₀	dBm	-6.0	-	2.4	1
Extinction Ratio	ER	dB	3	-	-	
Optical Receiver Characteristics						
Bit Rate	BR	Gbps	1.25	10.3125	-	Per lane
Sensitivity@BER=E-12	BER	dBm	-	-	-11.1	
Overload Input Optical Power	P _{IN}	dBm	2.4	-	-	2
Center Wavelength Range	λ_c	nm	840	-	860	
LOS Assert	-	dBm	-30	-	-	
LOS De-Assert	-	dBm	-	-	-12	
LOS Hysteresis	-	dB	0.5	-	-	

Note:

1. Coupled into 50/125 MMF.
2. Measured with PRBS 231-1 test pattern @10.3125Gbps.BER=E-12

Recommended Interface Circuit

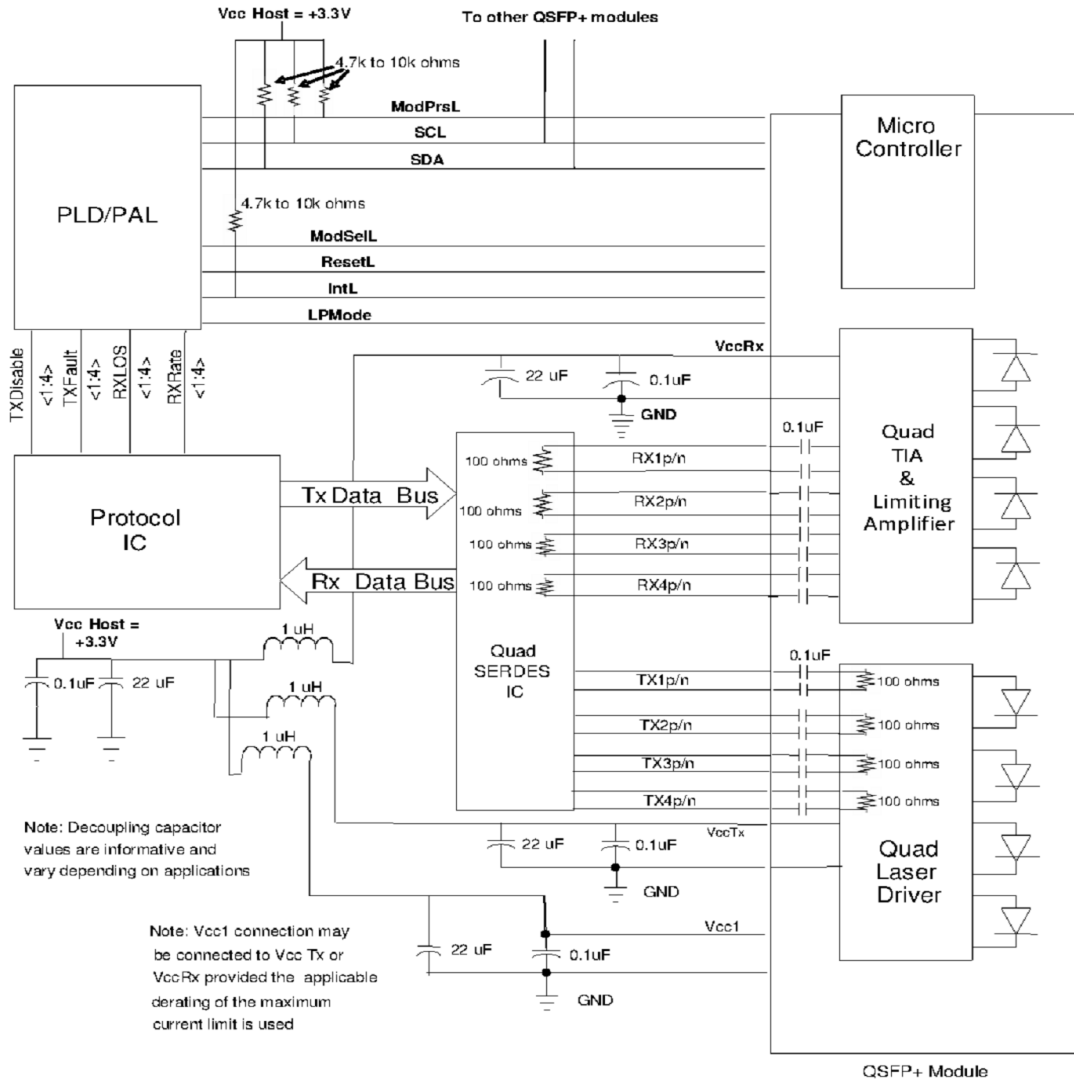


Figure 1, Recommended Interface Circuit

Pin arrangement

38	GND
37	TX1n
36	TX1p
35	GND
34	TX3n
33	TX3p
32	GND
31	LPMODE
30	Vcc1
29	VccTx
28	IntL
27	ModPrsL
26	GND
25	RX4p
24	Rx4n
23	GND
22	RX2p
21	RX2n
20	GND

Top Side
Viewed From Top

GND	1
TX2n	2
TX2p	3
GND	4
TX4n	5
TX4p	6
GND	7
ModselL	8
ResetL	9
VccRx	10
SCL	11
SDA	12
GND	13
RX3p	14
Rx3n	15
GND	16
RX1p	17
RX1n	18
GND	19

Bottom Side
Viewed From Bottom

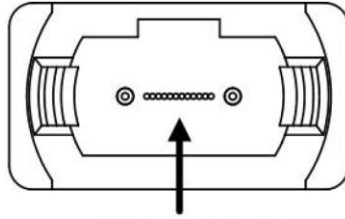
Figure 2, Pin View

Table 6-Pin Function Definitions

Pin	Symbol	Name/Description	Notes
1	GND	Ground	1
2	Tx2n	Transmitter Inverted Data Input	
3	Tx2p	Transmitter Non-Inverted Data Input	
4	GND	Ground	1
5	Tx4n	Transmitter Inverted Data Input	
6	Tx4p	Transmitter Non-Inverted Data Input	
7	GND	Ground	1
8	ModSelL	Module Select	
9	ResetL	Module Reset	
10	Vcc Rx	+3.3V Power Supply Receiver	
11	SCL	2-wire serial interface clock	
12	SDA	2-wire serial interface data	
13	GND	Ground	1
14	Rx3p	Receiver Non-Inverted Data Output	
15	Rx3n	Receiver Inverted Data Output	
16	GND	Ground	1
17	Rx1p	Receiver Non-Inverted Data Output	
18	Rx1n	Receiver Inverted Data Output	
19	GND	Ground	1
20	GND	Ground	1
21	Rx2n	Receiver Inverted Data Output	
22	Rx2p	Receiver Non-Inverted Data Output	
23	GND	Ground	1
24	Rx4n	Receiver Inverted Data Output	
25	Rx4p	Receiver Non-Inverted Data Output	
26	GND	Ground	1
27	ModPrsL	Module Present	
28	IntL	Interrupt	
29	Vcc Tx	+3.3V Power supply transmitter	
30	Vcc1	+3.3V Power supply	
31	LPMODE	Low Power Mode	
32	GND	Ground	1
33	Tx3p	Transmitter Non-Inverted Data Input	
34	Tx3n	Transmitter Inverted Data Input	
35	GND	Ground	1
36	Tx1p	Transmitter Non-Inverted Data Input	
37	Tx1n	Transmitter Inverted Data Input	
38	GND	Ground	1

Note: 1. Circuit ground is internally isolated from chassis ground.

Optical interface arrangement



Fiber Number: 12 11 10 9 4 3 2 1
 Transmit Channels: 1 2 3 4
 Receive Channels: 4 3 2 1

Figure 3, Optical interface arrangement. Lens upwards.

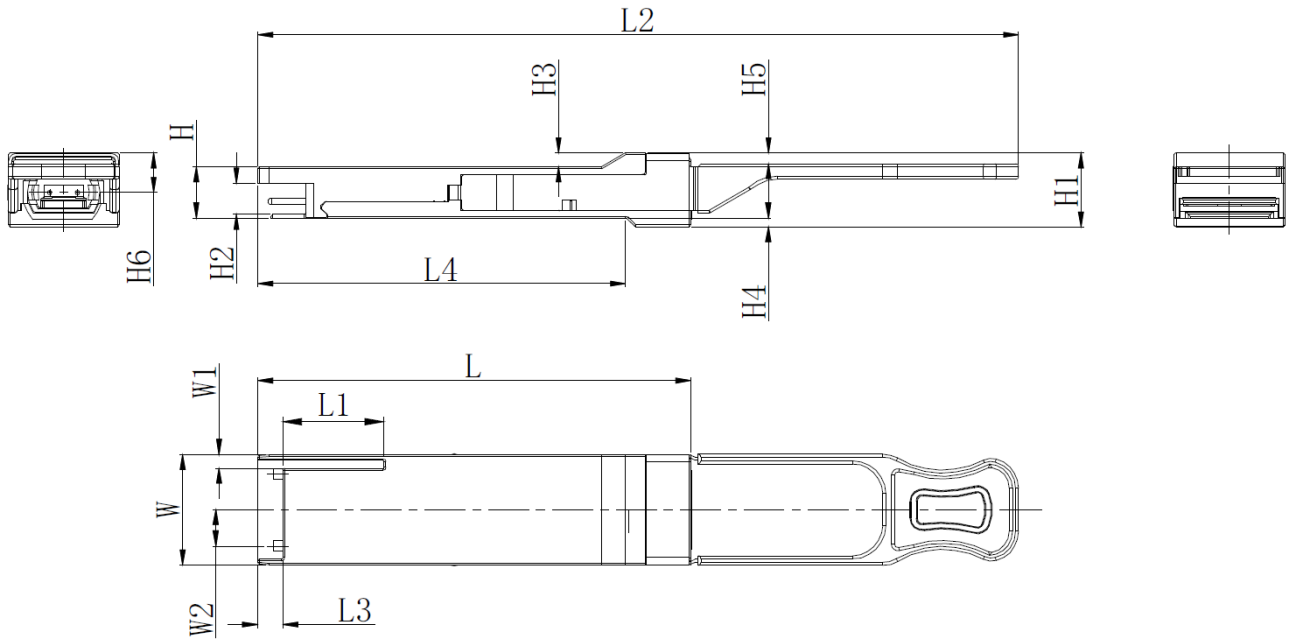
Monitoring Specification

2-Wire Serial Address 1010000x	
Lower Page 00h	
0	Identifier
1- 2	Status
3- 21	Interrupt Flags
22- 33	Free Side Device Monitors
34- 81	Channel Monitors
82- 85	Reserved
86- 98	Control
99	Reserved
100-104	Hardware Interrupt Pin Masks
105-106	Vendor Specific
107	Reserved
108-110	Free Side Device Properties
111-112	Assigned for use by PCI Express
113	Free Side Device Properties
114-118	Reserved
119-122	Password Change Entry Area (Optional)
123-126	Password Entry Area (Optional)
127	Page Select Byte

Upper Page 00h	Optional Page 01h	Optional Page 02h	Optional Page 03h
128 Identifier	128 CC_APPS	128-255 User EEPROM Data	128-175 Free Side Device Thresholds
129-191 Base ID Fields	129 AST Table Length (TL)		
	130-131 Application Code Entry 0		
	132-133 Application Code Entry 1		
	134-253 other entries		
192-223 Extended ID			176-223 Channel Thresholds
224-255 Vendor Specific ID			224 Tx EQ & Rx Emphasis Magnitude ID
			225 RX output amplitude indicators
			226-241 Channel Controls
			242-251 Channel Monitor Masks
	254-255 Application Code Entry TL		252-255 Reserved

Figure 4, Memory Map

Mechanical



Unit mm

	L	L1	L2	L3	L4	W	W1	W2	H	H1	H2	H3	H4	H5	H6
Max	72.2	-	128	4.35	61.4	18.45	-	6.2	8.6	12.4	5.35	2.5	1.6	2.0	-
Type	72.0	-	-	4.20	61.2	18.35	-	-	8.5	12.2	5.2	2.3	1.5	1.8	6.55
Min	68.8	16.5	124	4.05	61.0	18.25	2.2	5.8	8.4	12.0	5.05	2.1	1.3	1.6	-

Figure 5, Mechanical Diagram

Warnings

Handling Precautions: This device is susceptible to damage as a result of electrostatic discharge (ESD).

A static free environment is highly recommended. Follow guidelines according to proper ESD procedures.

Laser Safety: Radiation emitted by laser devices can be dangerous to human eyes. Avoid eye exposure to direct or indirect radiation.